

SOT774-1

plastic low profile ball grid array package; 208 balls; body 17 x 17 x 1.05 mm

8 February 2016

Package information

1. Package summary

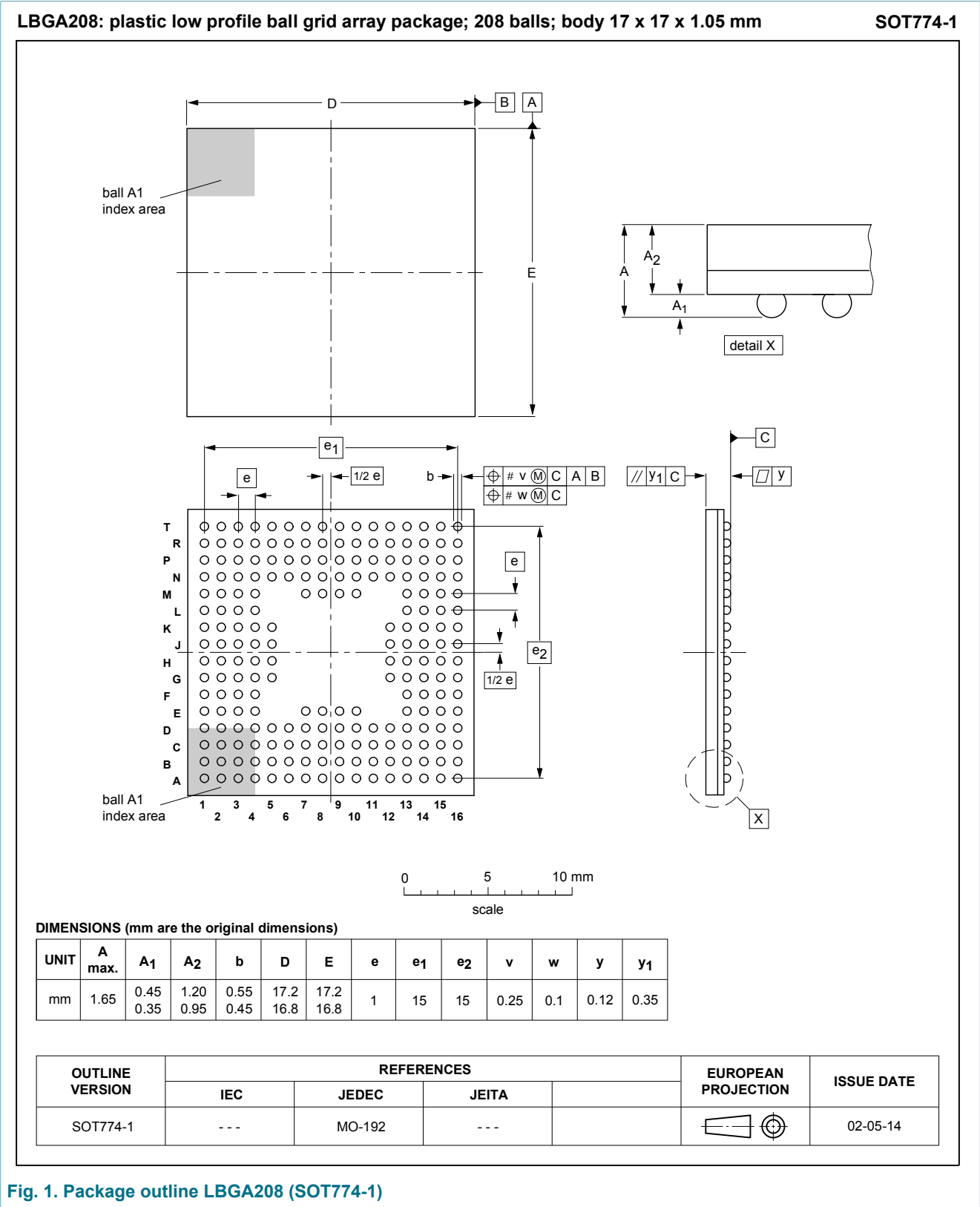
Terminal position code	B (bottom)
Package type descriptive code	LBGA208
Package type industry code	LBGA208
Package style descriptive code	LBGA (low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-192
Mounting method type	S (surface mount)
Issue date	14-5-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		16.8	-	17	17.2	mm
E	package width		16.8	-	17	17.2	mm
A	seated height		[tbd]	-	1.65	1.65	mm
A ₂	package height		0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination		-	-	208	-	



2. Package outline



3. Soldering

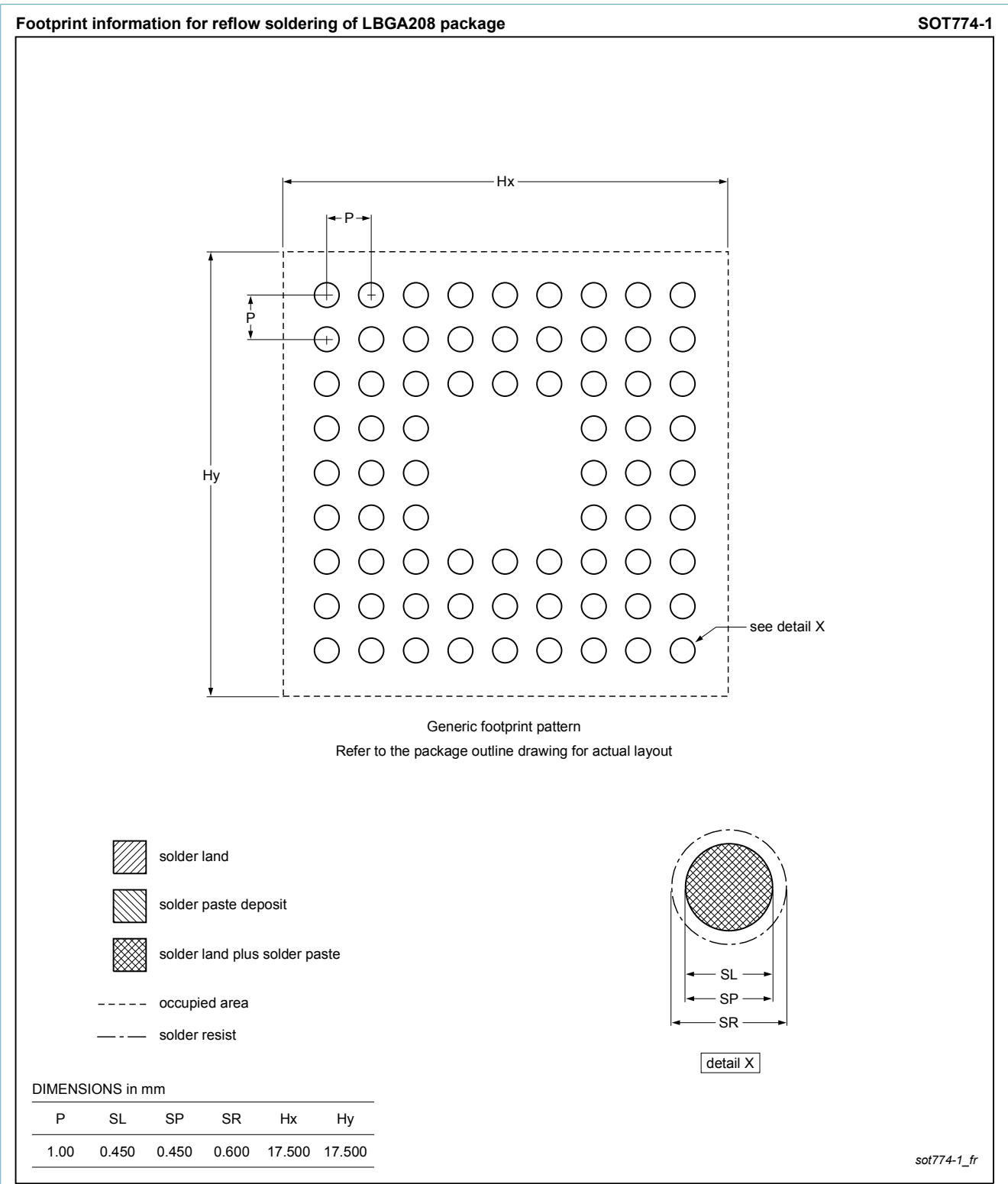


Fig. 2. Reflow soldering footprint for LBGA208 (SOT774-1)

4. Legal information

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